

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: GROSS, KATHLEEN B.

Application No.: 09/801,234

Group Art Unit: 1712

Filed: March 7, 2001

Examiner: Keehan, Christopher M.

Title: ADHESIVES AND ADHESIVE COMPOSITIONS CONTAINING
THIOETHER GROUPS

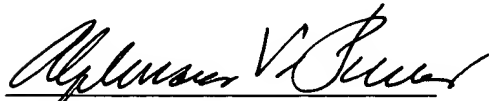
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DECLARATION UNDER 37 CFR § 1.131


We, Alphonsus V. Pocius and Wendy L. Thompson, individually and jointly, declare that:

1. We are Applicants of the above-identified patent application and coinventors of the subject matter described and claimed therein.
2. Prior to December 28, 2000, we completed work described below to substantiate the invention as described and claimed in the above-identified application in this country, as evidenced by the following:
 - a. The ingredients for adhesive compositions of the invention (of the above-identified patent application) are shown in Notebook 118288, page 39, lines 5-14 and lines 30-32 (see Exhibit A). The adhesive compositions described in Exhibit A are similar to those of Example 4 in the above-identified patent application and contain the epoxy reactive thioether-containing compound of Example 1 in the above-identified patent application.
 - b. The claimed ingredients for the adhesives of the invention (of the above-identified patent application) are shown in Notebook 118288, page 39, lines 5-14, lines 20-30, and lines 30-32 (see Exhibit A). Lines 20-30 of Exhibit A describe curing the adhesive compositions of Exhibit A using DSC to cure the adhesive compositions to form adhesives.

- c. Use of adhesive compositions and adhesives of the invention to bond to a polyimide surface to form an article is described in Notebook 118415, page 76, lines 15-35 (See Exhibit B). Adhesive 39D of Exhibit B refers to composition D of Notebook 118288, page 39 (Exhibit A). Adhesive 41 B refers to composition B of Notebook 118288, page 41 (Exhibit C) and contains the epoxy reactive thioether-containing compound of Example 1 of the above-identified application.
- d. EPON 1462 (RSL 1462)(epoxy resin) and DEH 85 (epoxy curative) are defined in the specification at page 8.
3. The work described in paragraph 2 above was done in the United States.
4. The adhesive compositions, adhesives, bonded articles, and uses of the adhesives as described in Exhibits A, B, and C, as outlined above, provide support for the independent claims (Claims 1, 8, 11, 21, and 28) of the above-identified application.
5. Each of the dates deleted from Exhibits A, B, and C is prior to December 28, 2000.
6. The undersigned declares further that all statements made herein of their own knowledge are true, and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful, false statements and the like are punishable by a fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful, false statements may jeopardize the validity of the application or any patent issuing thereon.


Alphonsus V. Pocius

4/21/2003
Date


Wendy L. Thompson

4/21/2003
Date